

COMBINED DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **COMPLEX LAMINATED CHIP ELEMENT**, the specification of which:

☒ is attached hereto.  
☐ was filed on \_\_\_\_\_ as Application No. \_\_\_\_\_  
☐ and was amended on \_\_\_\_\_ (if applicable)  
☐ with amendments through \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Sec. 119 (a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Claiming Priority?	
			Yes	No
<u>2003-0052561</u> (Number)	<u>Republic of Korea</u> (Country)	<u>30 July 2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/>	<input type="checkbox"/>
<u>2003-0052562</u> (Number)	<u>Republic of Korea</u> (Country)	<u>30 July 2003</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/>	<input type="checkbox"/>

I hereby claim the benefit under Title 35, United States Code, Sec. 119(e) of any United States provisional application listed below:

Provisional Application No.

Filing Date

\_\_\_\_\_

\_\_\_\_\_

I hereby claim the benefit under Title 35, United States Code, Sec. 120 or §365(c) of any PCT international application designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>PCT/KR2004/001759</u>	<u>15 July 2004</u>	<u>Pending</u>
(Application No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby appoint the attorneys or agents associated with **Customer No. 20575** to represent the undersigned before the United States Patent and Trademark Office (USPTO) in connection with the above application.

Direct all telephone calls to Hosoon Lee at (503) 222-3613 and send all correspondence to the following address associated with **Customer No. 20575**:

MARGER JOHNSON & McCOLLOM, P.C.  
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Inventor's signature: \_\_\_\_\_ (Date)

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**Title of Invention:** COMPLEX LAMINATED CHIP ELEMENT

**U.S. Patent Application:**

Application Serial No.:

Filing Date:

For good and valuable consideration, the receipt of which is hereby acknowledged, the above-named Assignor hereby sells, assigns and transfers to Assignees, the full and exclusive right, title and interest in and to the above-identified invention, patent application and patent rights throughout the world, including foreign patent priority rights; said invention, application and letters patent in this or any foreign country, and all divisions, continuations, reissues and extensions thereof, to be held and enjoyed by Assignees in joint undivided one-fourth interest each, for their own use and benefit, and for their successors and assigns to the full end of the term for which letters patent may be granted in this or any foreign country, as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and covenant that Assignors have full right so to do, and agree that Assignors will communicate to Assignees, or its successors and assigns, any facts known to Assignors respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths, and do everything possible to aid Assignees, their successors and assigns to obtain and enforce proper patent protection for said invention in this or any foreign country; and Assignors hereby authorize and request the Commissioner of Patents to issue Letters Patent to Assignees.

Executed at \_\_\_\_\_, this \_\_\_\_\_ day of \_\_\_\_\_,  
City Country

2006.

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